Accepted Manuscript

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PII: S0040-6090(17)30685-5
DOI: doi: 10.1016/j.tsf.2017.09.018
Reference: TSF 36218

To appear in: *Thin Solid Films*

Received date: 9 December 2016
Revised date: 31 July 2017
Accepted date: 9 September 2017

Please cite this article as: Xiumei Zhang, Xiaofeng Gu, Shaoqing Xiao , Modification of SiO2 thickness distribution through evaporation, *Thin Solid Films* (2017), doi: 10.1016/j.tsf.2017.09.018

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